

In the claims

Please amend the claims as shown. A marked-up version of the amended claims is in Appendix A at the end of this document. A clean version of all pending claims after the amendment is shown below:

CLEAN VERSION OF CLAIMS AFTER AMENDMENT

19. (Amended four times) A method of assembling a multi-chip device comprising:

providing an interposer having a first surface and a second surface;

populating the second surface with a plurality of conductive pads;

coupling a solder ball to each of selected ones of the plurality of conductive pads;

coupling a plurality of semiconductor dice and at least one passive device to the first surface to form a multi-chip subassembly, wherein the at least one passive device is selected from a group comprising resistors, capacitors, and inductors;

testing said plurality of semiconductor dice on said interposer;

coupling said interposer to a substrate with the solder balls after said testing if said plurality of semiconductor dice passes said testing; and

coupling at least one other semiconductor device to the substrate.

21. (Amended twice) The method of claim 19 wherein providing comprises providing the interposer having organic material.

22. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises a C4 process.

Sub 837
23. (Amended three times) The method of claim 19 further comprising not coupling said interposer to the substrate if said plurality of semiconductor dice does not pass said testing.

24. (temporarily removed from consideration) (Amended once) The method of claim 19 further comprising coupling a single chip carrier to the substrate.

25. (temporarily removed from consideration) (Amended once) The method of claim 19 wherein coupling at least one semiconductor die comprises coupling memory chips to the interposer.

Sub 837
26. (Amended once) The method of claim 19, further comprising:
creating a plurality of contacts on the substrate; and
electrically connecting said selected ones of the plurality of conductive pads to the plurality of contacts.